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THE UNIVERSITY of EDINBURGH
Institute for Integrated Micro and Nano Systems

Over 2 Million Frames per Second 128×128 Macropixel 3D-Stacked Burst SPAD-Based Image Sensor

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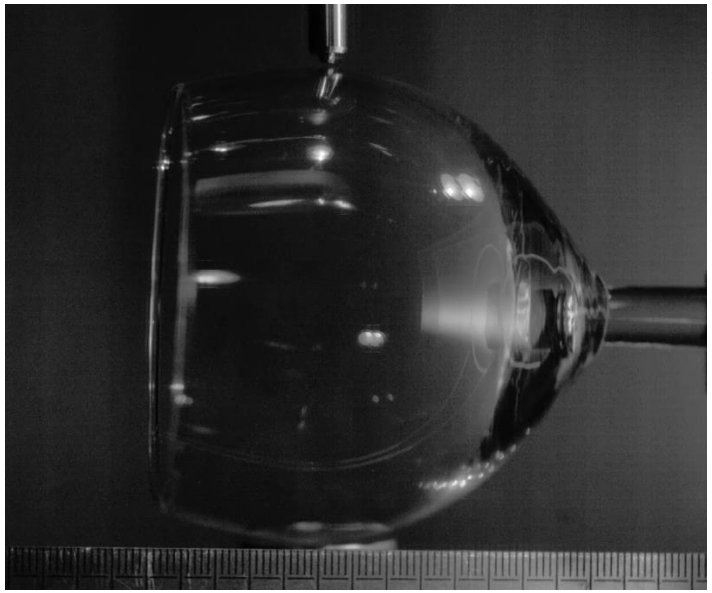
Engineering and Physical Sciences Research Council

Transient phenomena occurring at extremely short timescales

33k fps



G. Cai et al, A 1.3M Pixel 34,700fps Global-Shutter BSI Imager with HDR and Motion Blur Suppression Capability, IISW, 2021

76k fps

D. Van Blerkom et al, A 1Mpixel, 80k fps Global Shutter CMOS Image Sensor for High Speed Imaging, IISW, 2021

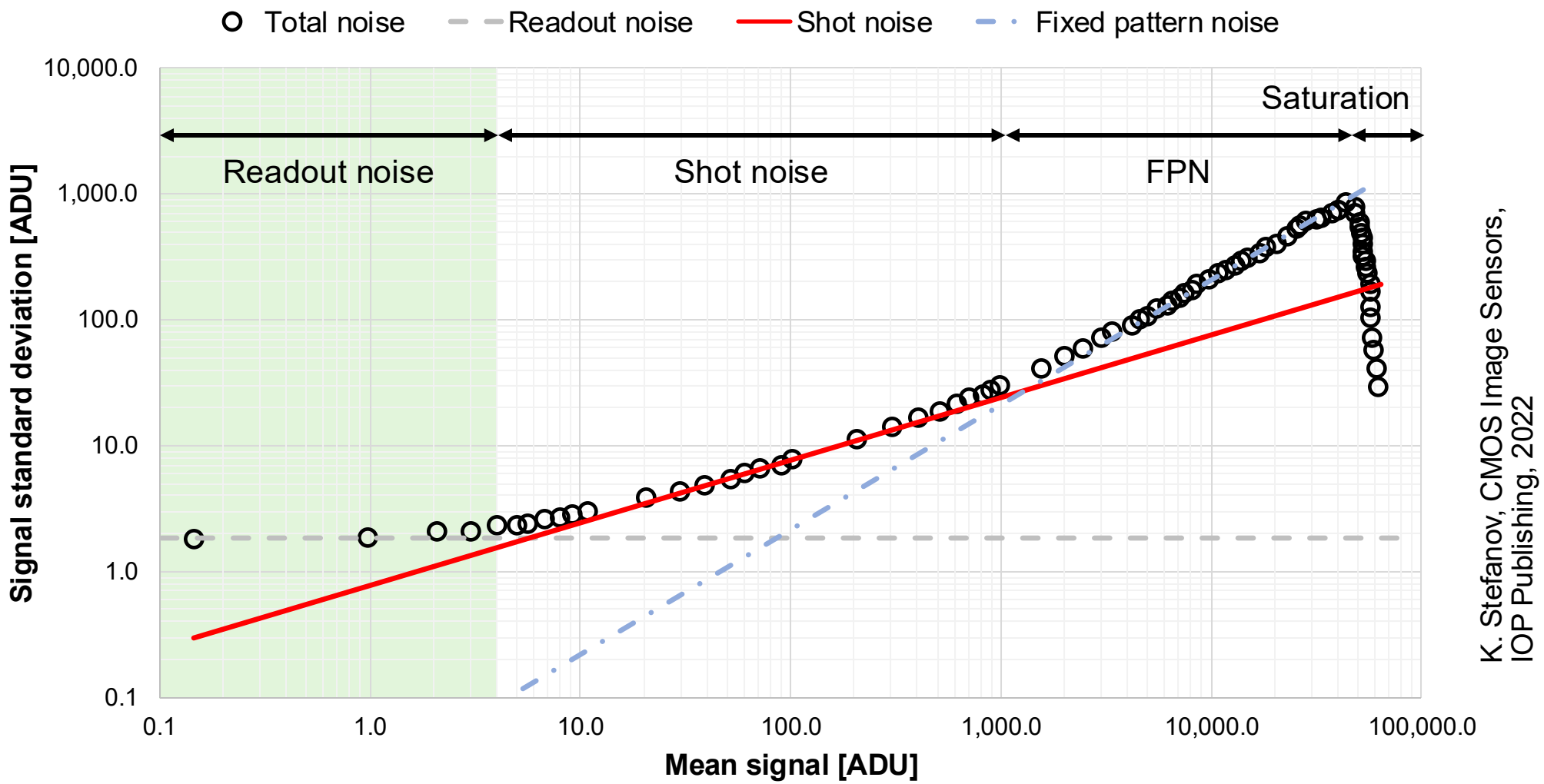
5M fps

https://www.youtube.com/watch?v=DxW23n8kid8 and S. Shigetoshi et al., A 20 Mfps global shutter CMOS image sensor with improved sensitivity and power consumption, IISW, 2015

Due to ultra-short integration times, high-speed imaging is often also low-light imaging.

Low Number of Photons

Photon Transfer Curve (CIS)



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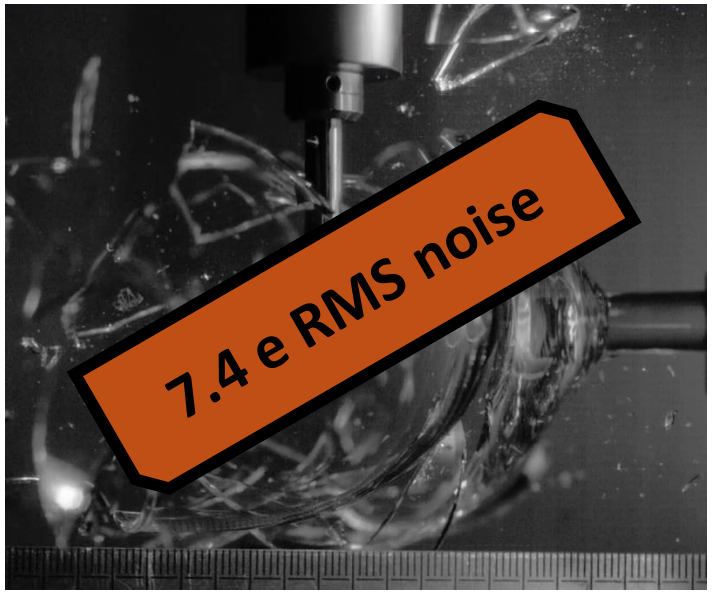

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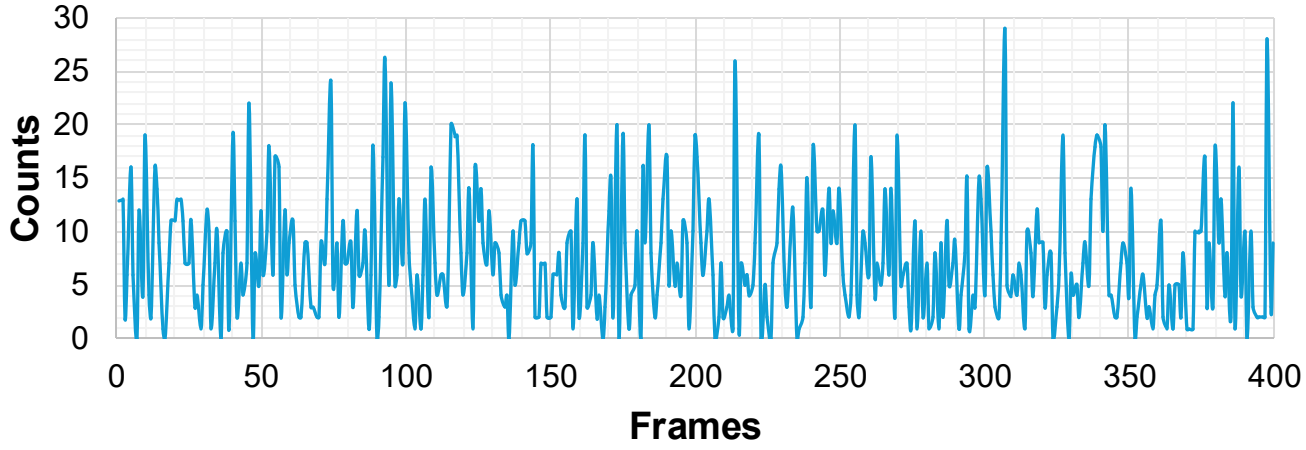
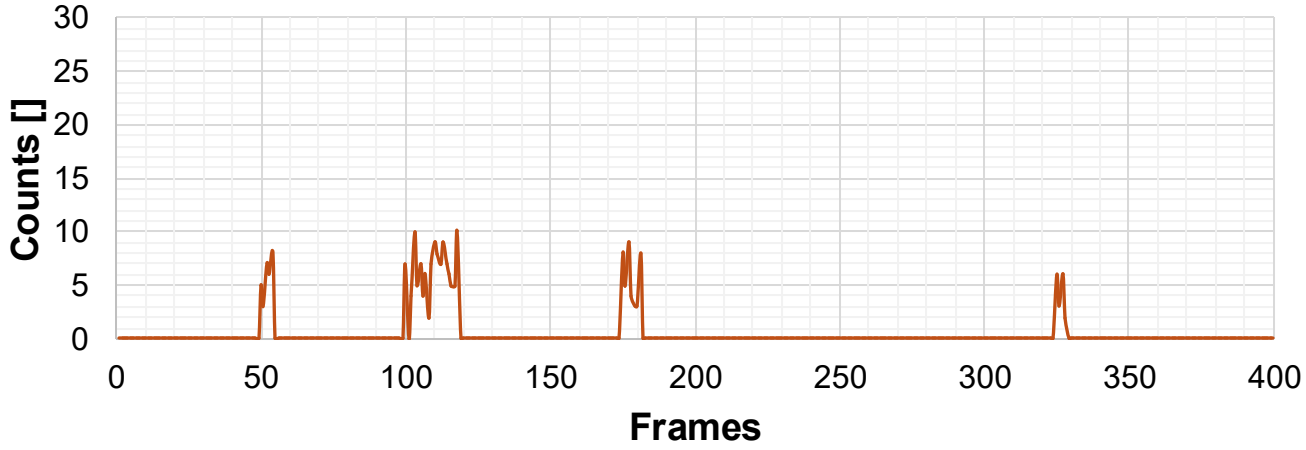
Readout Noise in Photon-Starved Imaging

Analogue CIS



- 10 e RMS readout noise is simulated without any input signal.
- A signal of 5 photons is added at four time instances.

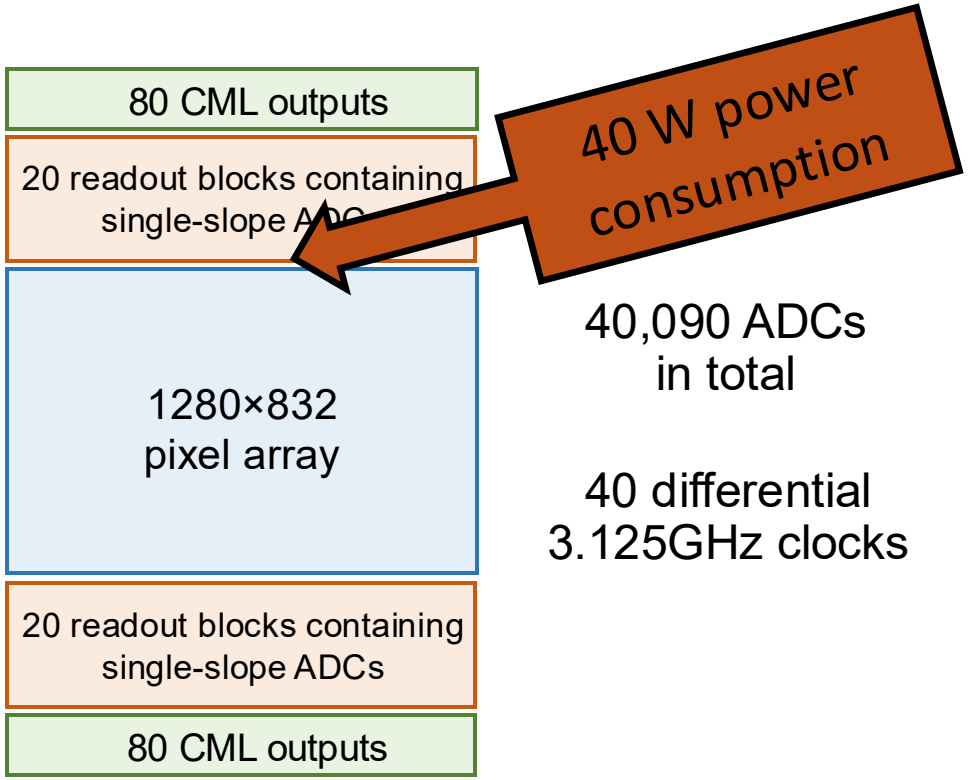
SPAD



- Zero readout noise.
- Signal is signified at four time instances.

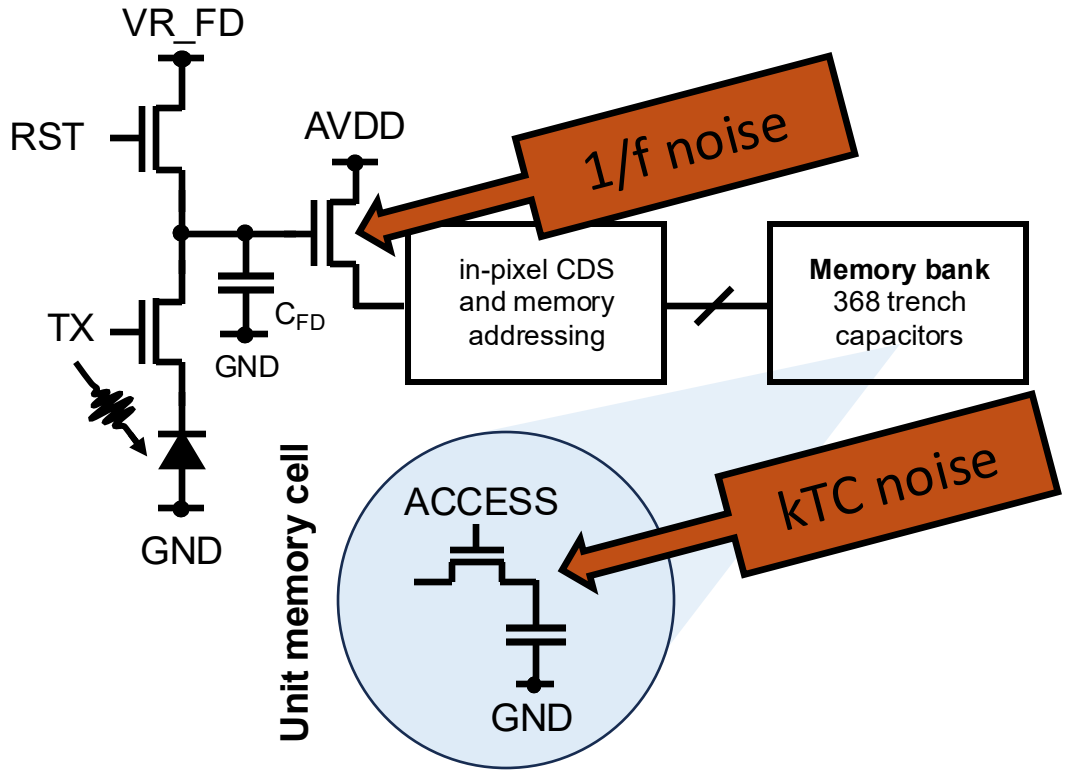
State-of-the-Art High-Speed CIS Design Techniques

Massively-Parallelized Readout and ADCs



D. Van Blerkom et al, A 1Mpixel, 80k fps Global Shutter CMOS Image Sensor for High Speed Imaging, IISW, 2021

368-Frames Burst Capture Pixel

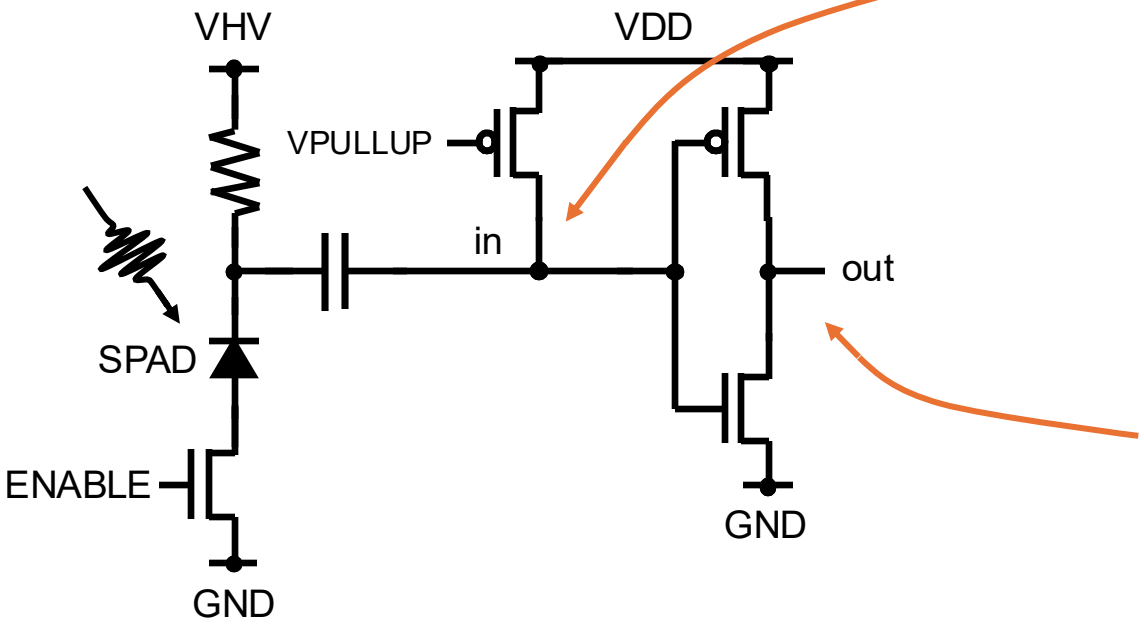


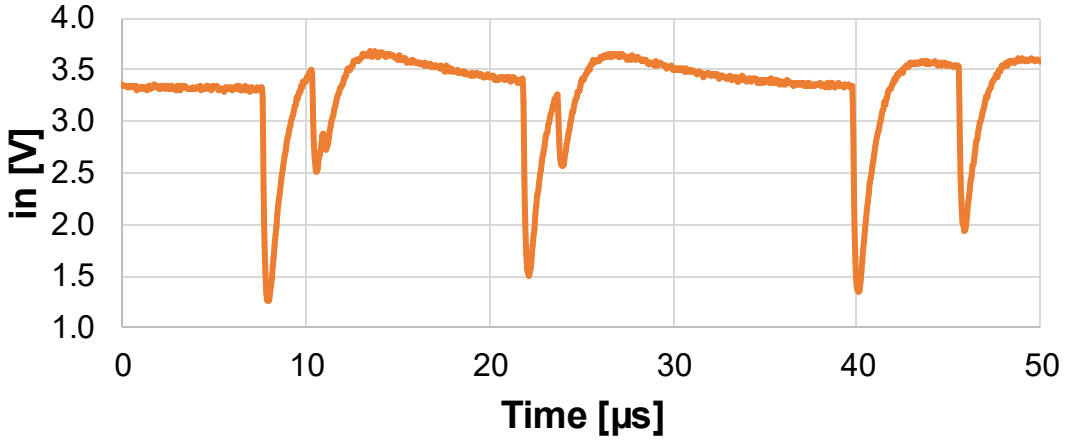
S. Manabu, Over 100 Million Frames per Second 368 Frames Global Shutter Burst CMOS Image Sensor with In-pixel Trench Capacitor Memory Array, IISW, 2019

SPAD-Based Imaging

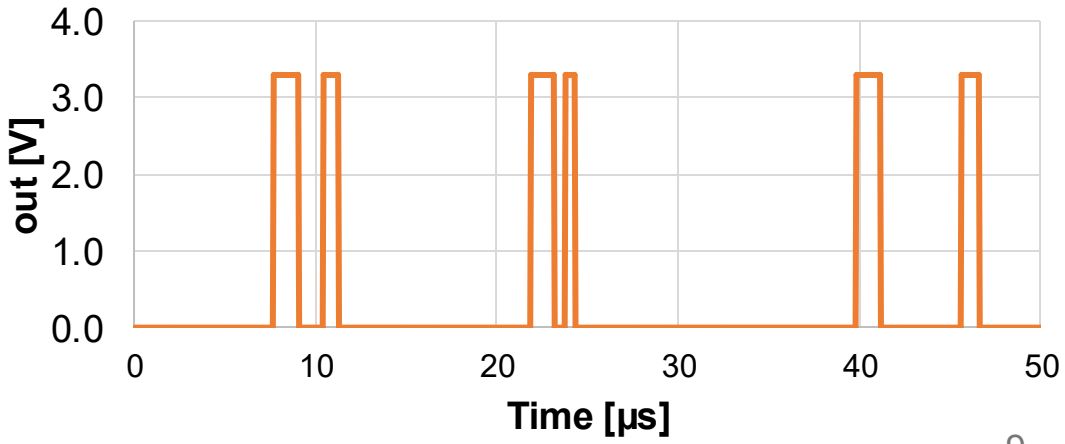
- Detection of single photons via avalanche multiplication.
- The avalanche is sensed by a frontend circuit and then quenched by a resistor.

No readout noise



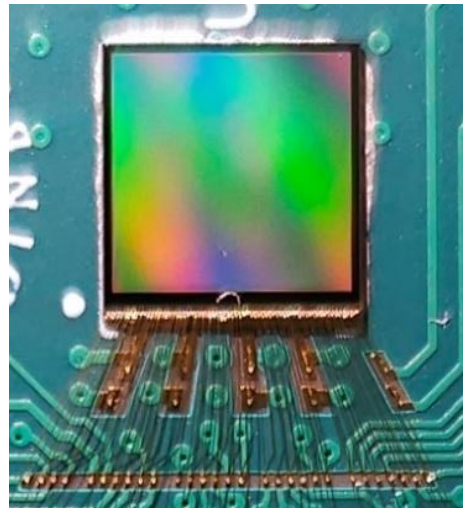


- Rising edge signals the arriving photon.

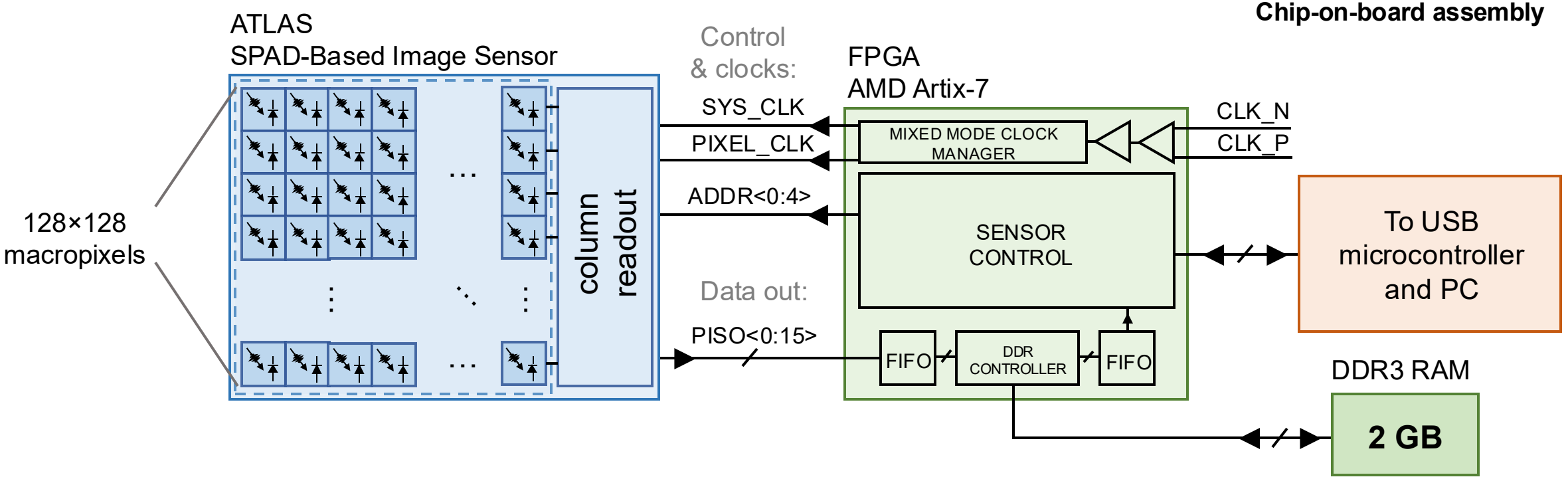


128×128 Macropixel SPAD Sensor and Camera

- 3-D-stacked back-side illuminated SPAD 512×512 SPAD imager.
- Sensor and the camera system capable of 2.18M fps burst imaging.
- Manufactured in STMicroelectronics' 3D40SPAD process.

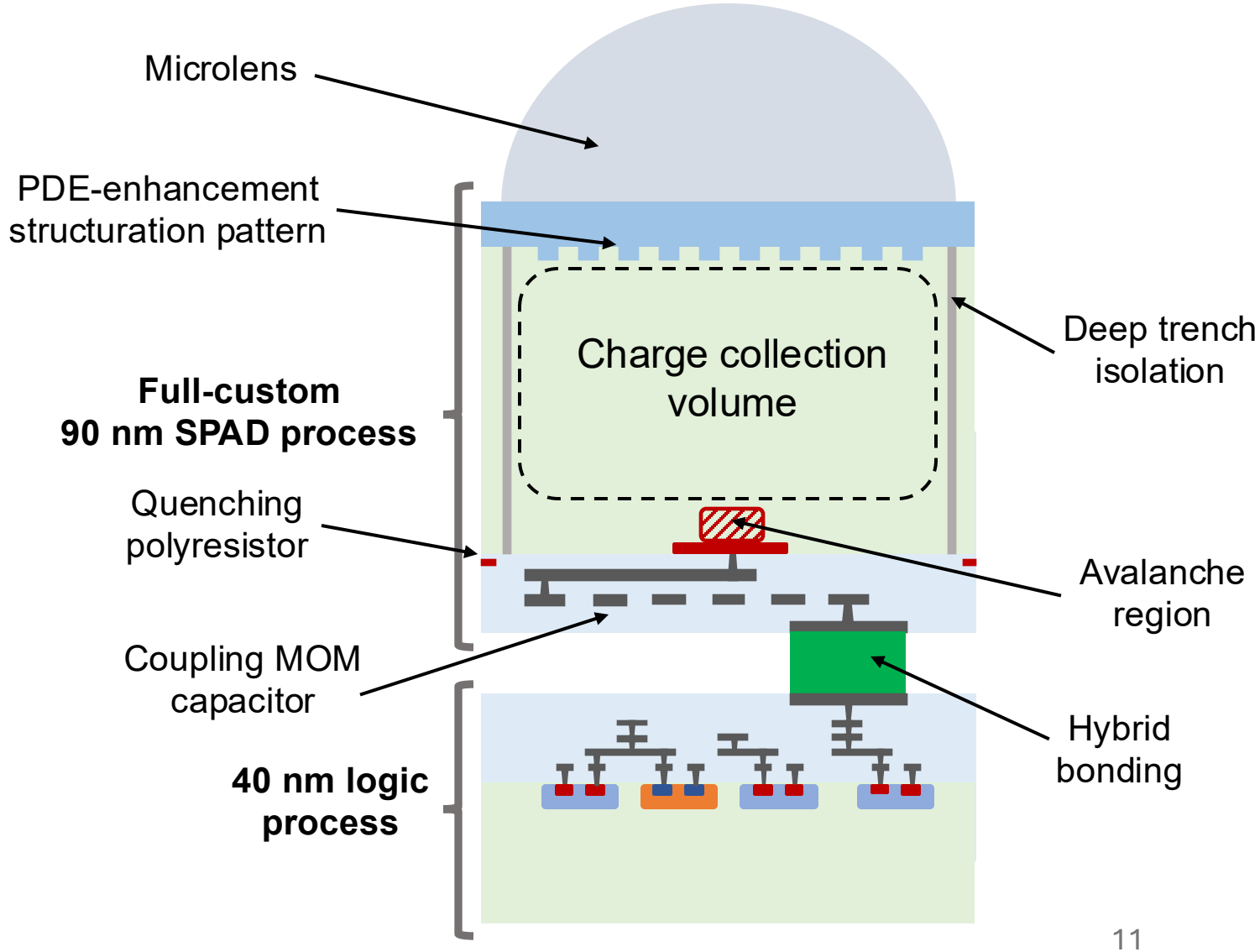


Chip-on-board assembly



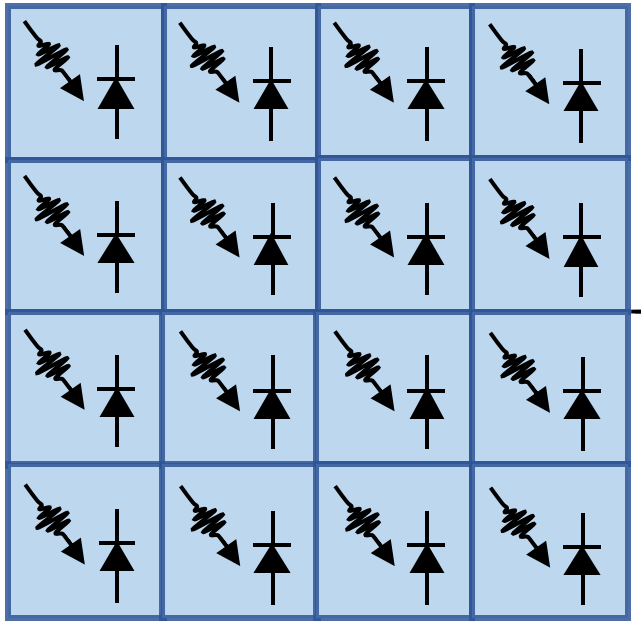
3-D-Stacked SPAD (Peak PDE=55%)

- Two wafers for light sensing and signal processing are made in two independently optimized processes.
- Top tier contains the SPAD device, quenching resistor and AC-coupling capacitor.
- Bottom tier contains CMOS transistors.
- Approx. 100% fill factor and low DCR are achieved while complex circuits can be integrated within the pixel.

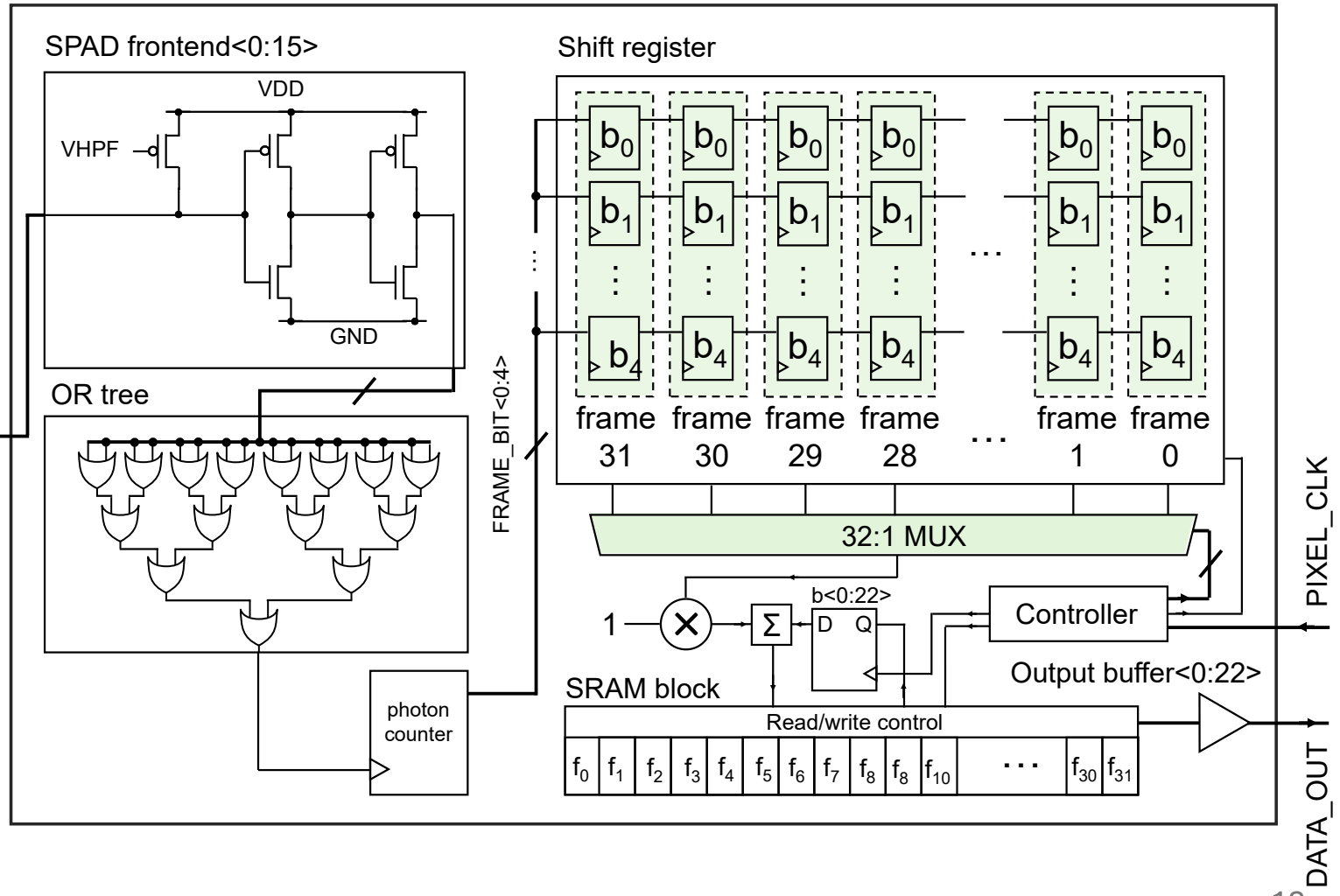


Macropixel Architecture

Top tier:
passively-quenched SPADs



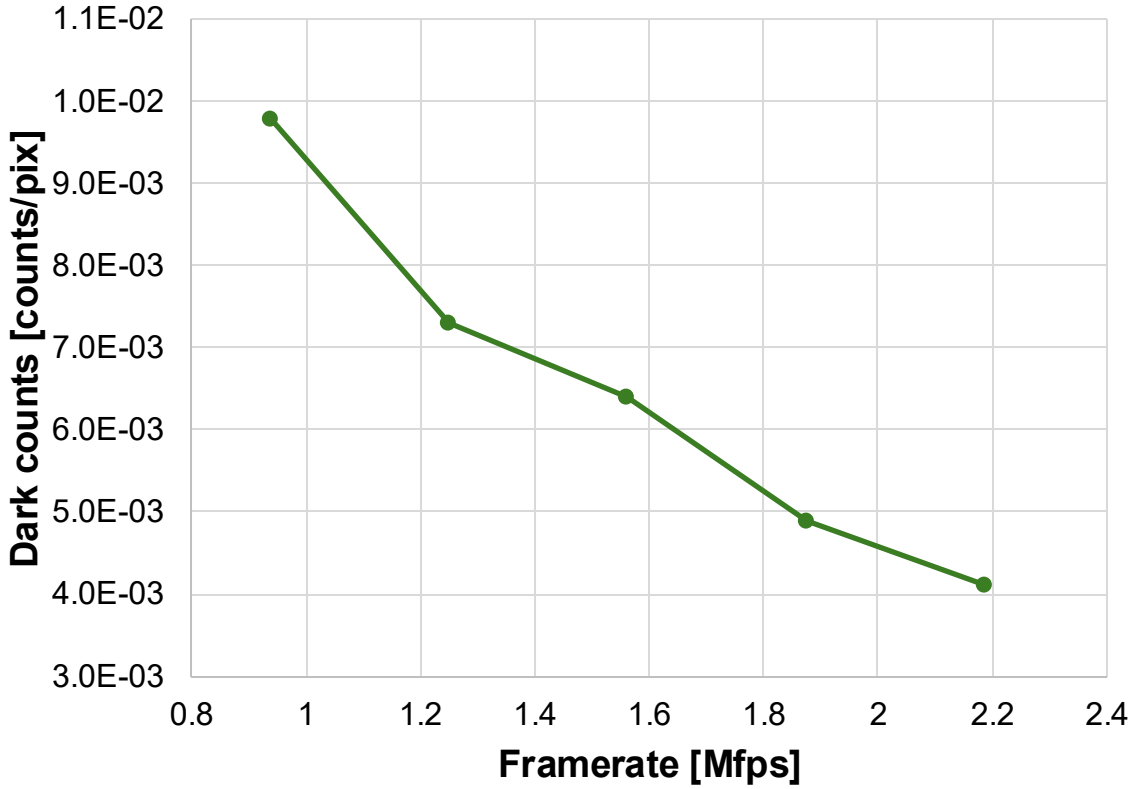
Bottom tier: pixel logic circuits



Characterization

1. Dark Counts vs. Framerate
2. Transfer Curve
3. LED Imaging
4. LED Blinking Test
5. High Speed Air Blaster

DCR vs. Framerate



Measurement Conditions:

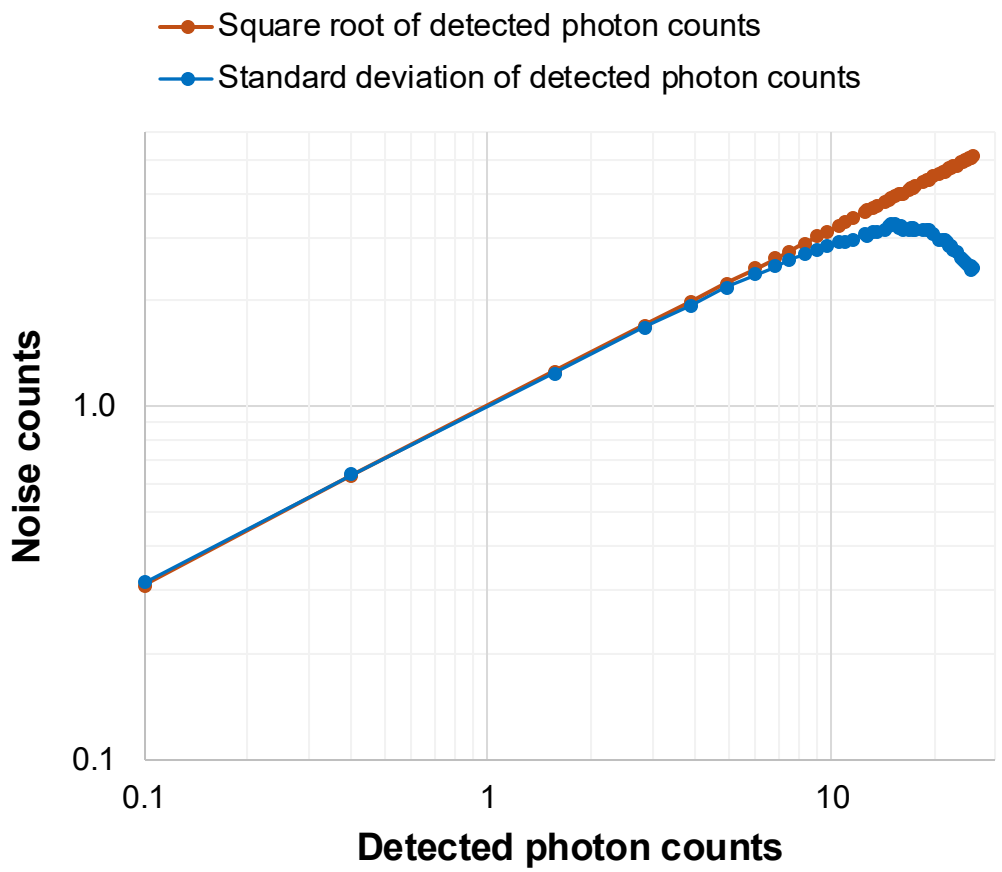
- Room temperature
- Complete light shielding
- 100 frames for each point
- Each point is averaged over 1,638,400 pixels

Shorter integration times are reducing thermally generated noise events in one frame

» Dark counts decrease as framerate increases

Noise Measurement

$$\sigma_{total}^2 = \sigma_{shot}^2 + \sigma_{readout}^2$$



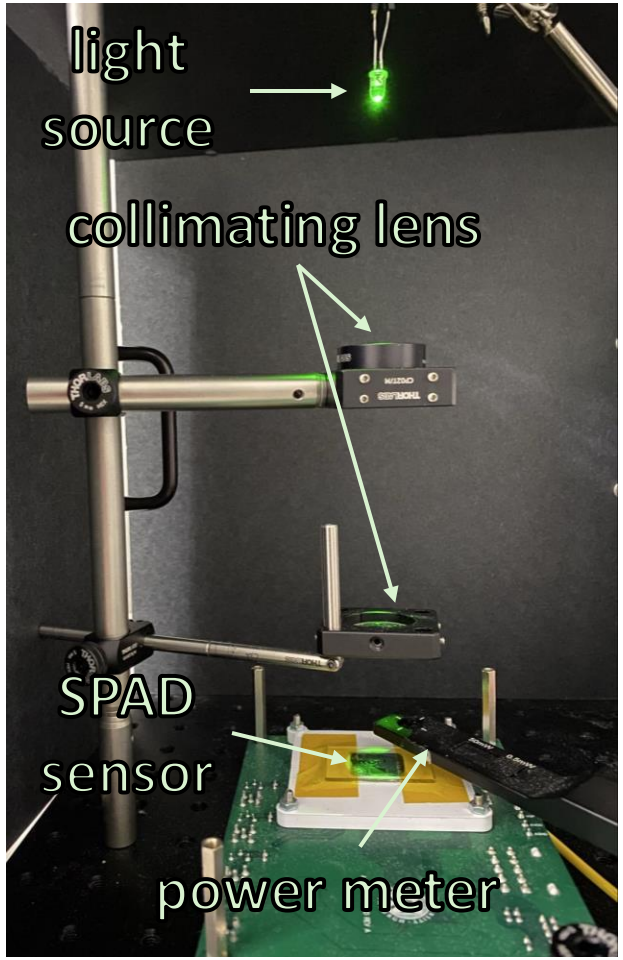
No slope-zero regime observed

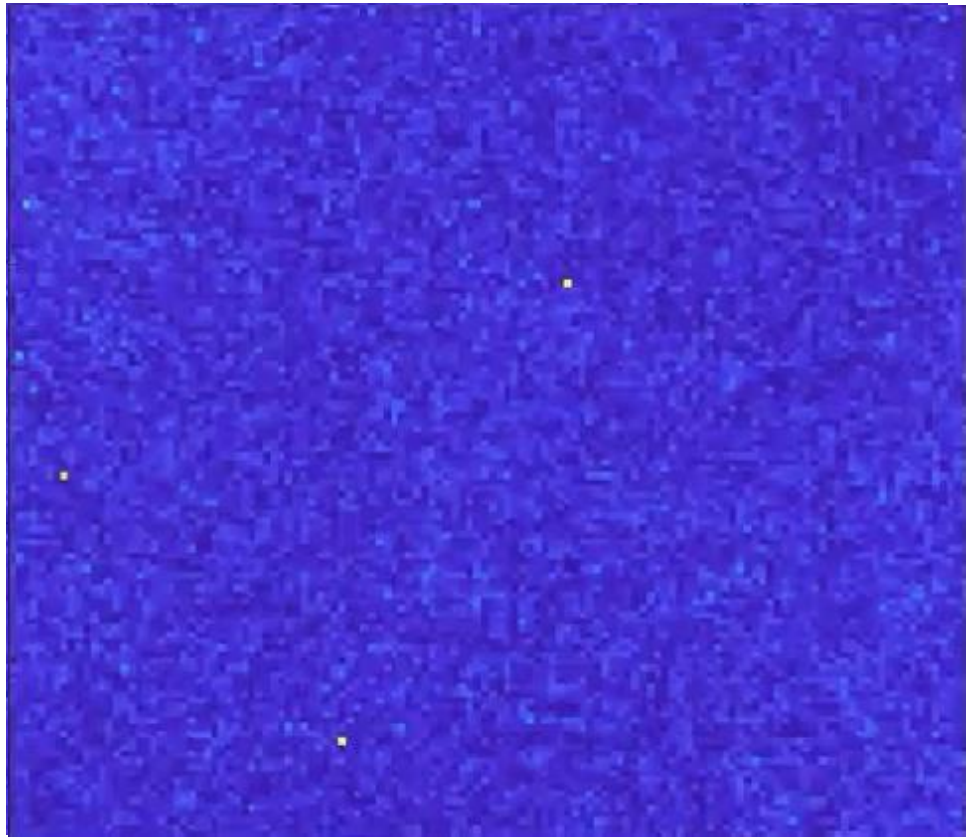
Measurement Conditions:

- Room temperature
- Power meter is applied to ensure linear photon counts increase
- Captured at 2.18 Mfps using collimated light
- 20 consecutive frames for each point
- Each point is calculated from 1,638,400 pixels

No readout noise, shot noise is the only limitation

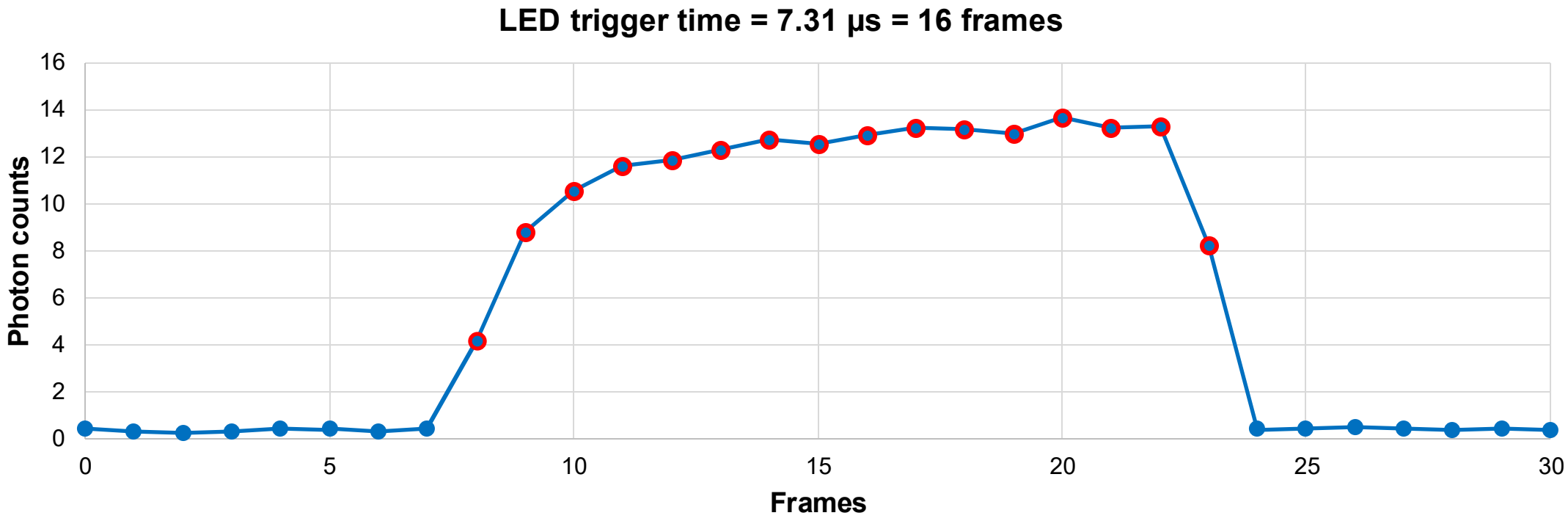
System Functionality Test





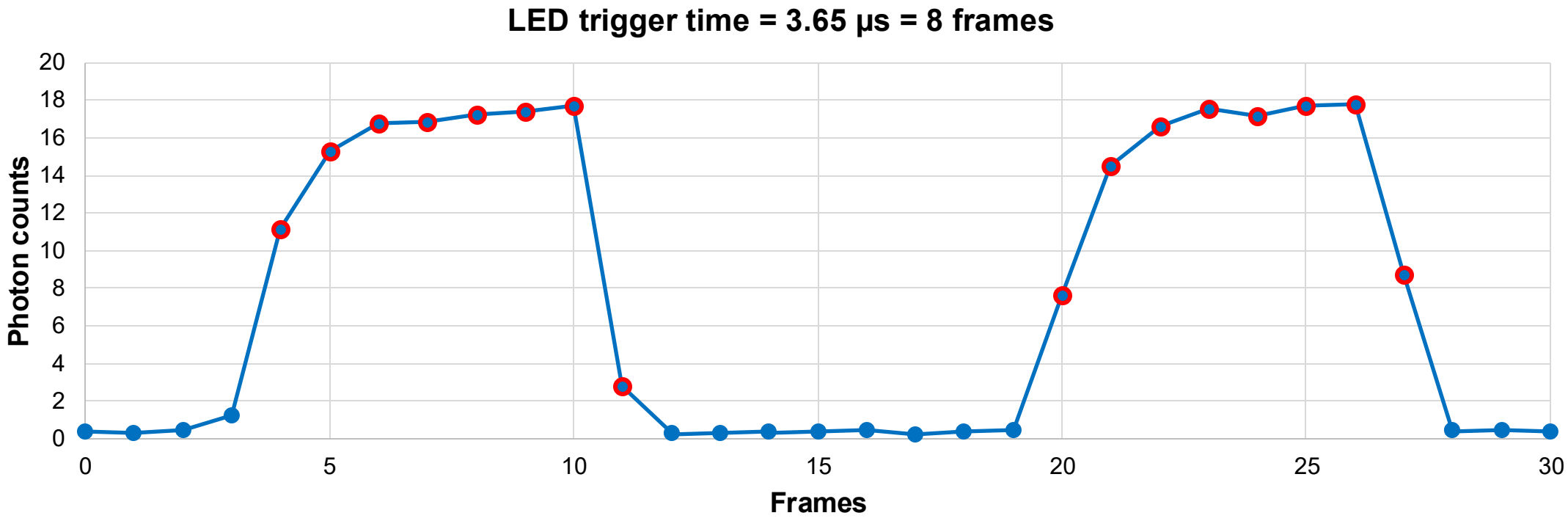
378 kHz LED @ 625k fps

Experiment Proving 2.18M fps Framerate



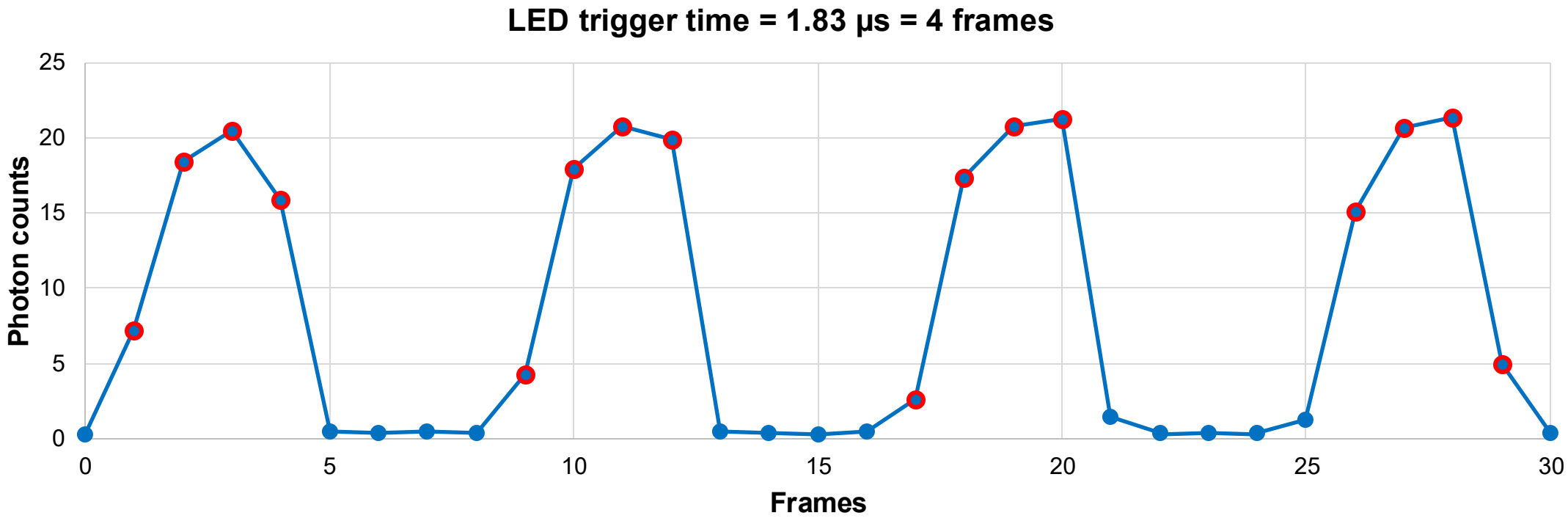
LED blinking frequency: 68 kHz

Experiment Proving 2.18M fps Framerate



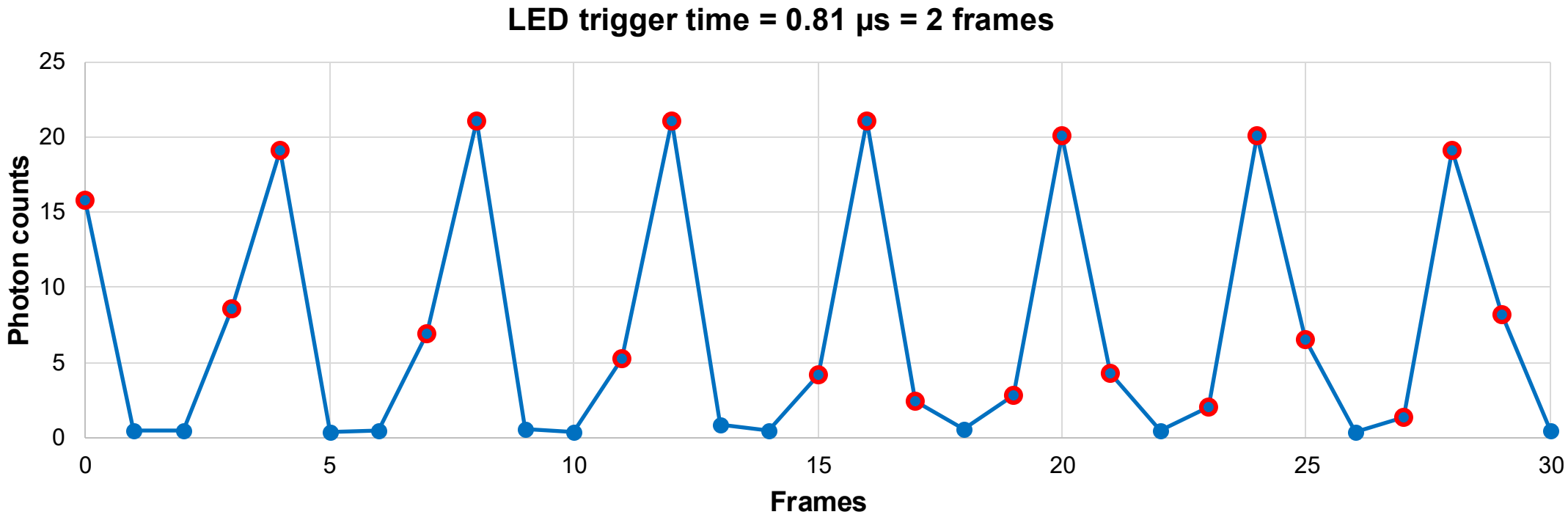
LED blinking frequency: 136 kHz

Experiment Proving 2.18M fps Framerate



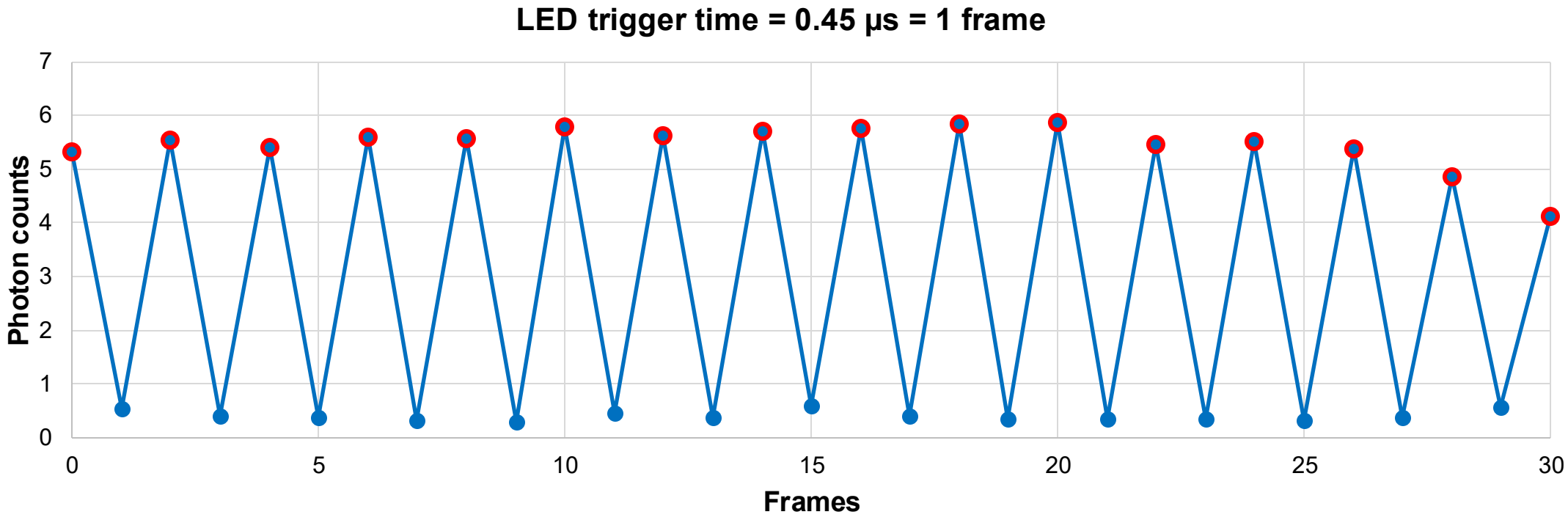
LED blinking frequency: 273 kHz

Experiment Proving 2.18M fps Framerate



LED blinking frequency: 547 kHz

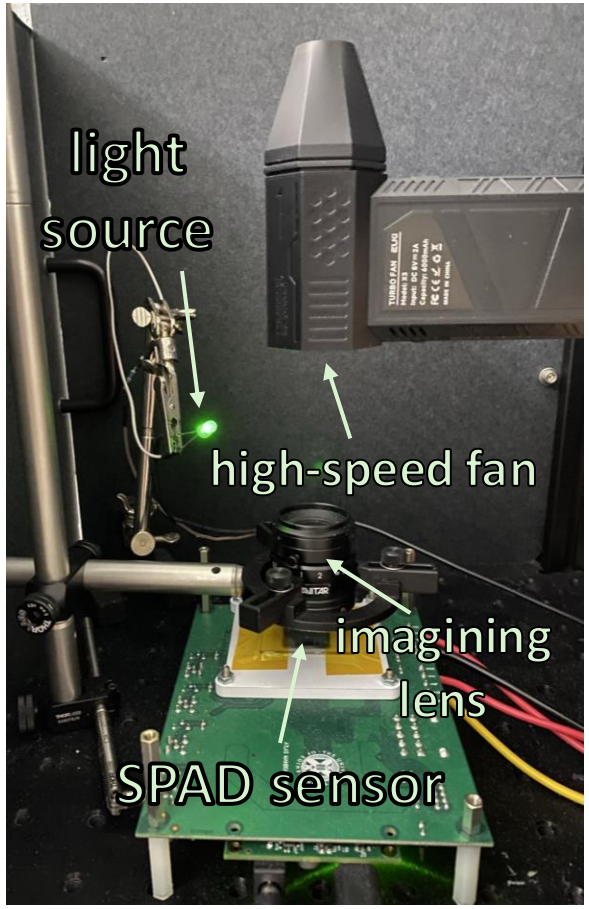
Experiment Proving 2.18M fps Framerate

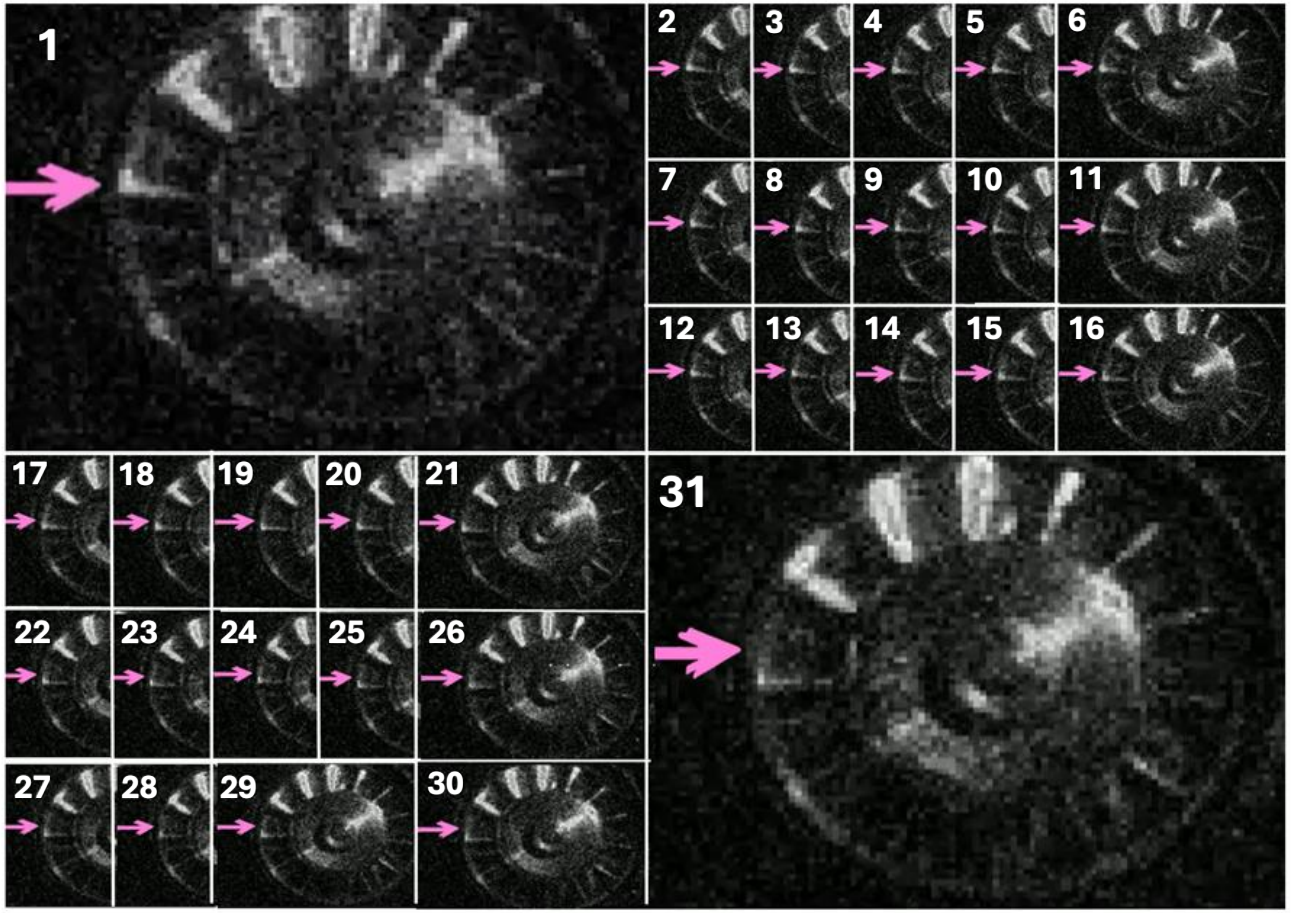


LED blinking frequency: 1094 kHz

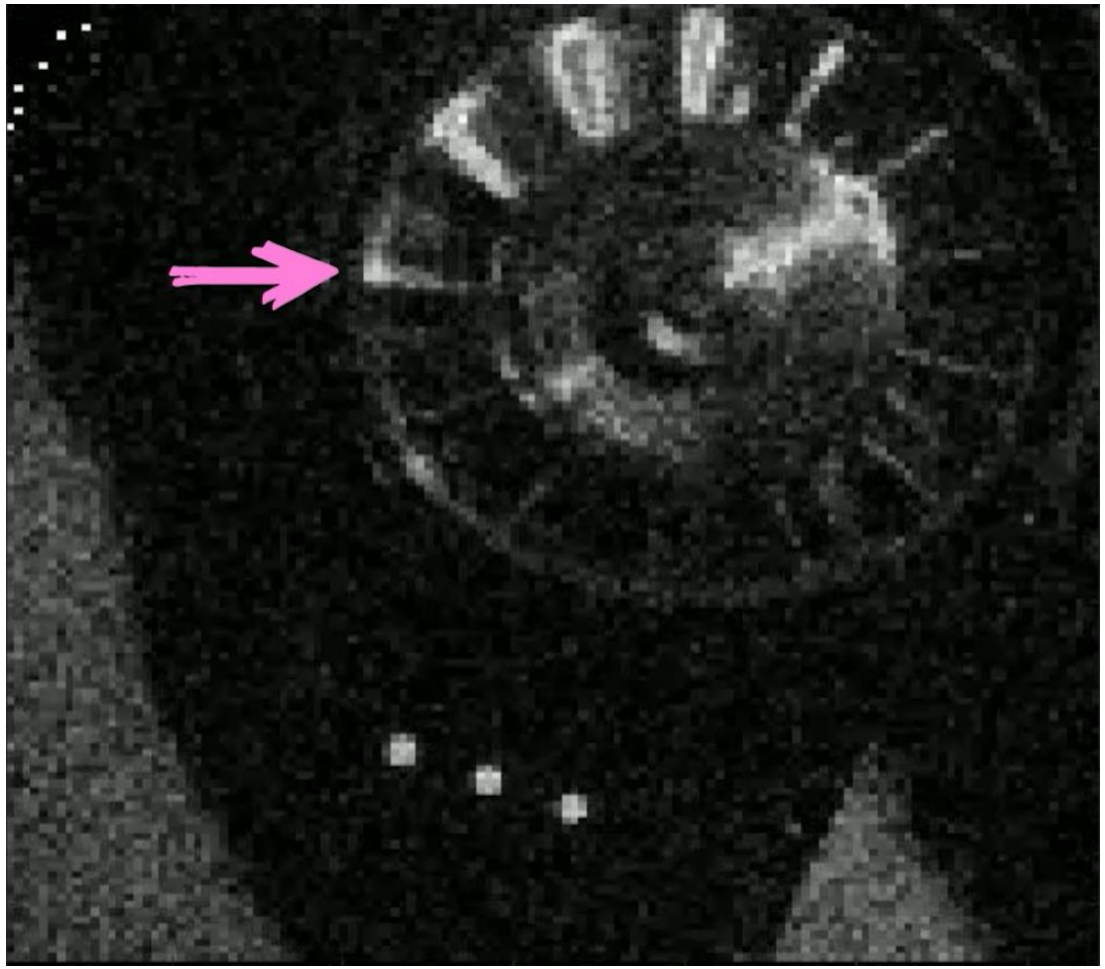
Transient Event Imaging

using a 150,000-rpm air-blaster fan





Transient Event Imaging



- Declared fan speed: 150,000 rpm
- Captured 32-frame burst
- Blade rotation angle: 8° over 31 frames
- Observed fan speed: 102,000 rpm

State-of-the-Art Comparison

Parameter	This work	S. Shigetoshi [1]	S. Manabu [5]	V. Dao [6]	D. Van Blerkom [3]
Technology	3-D-stacked 90 nm BSI / 40 nm	180 nm	180 nm	BSI	110 nm BSI
Imaging device	SPAD	Pinned photodiode	Pinned photodiode	CCD	Partially-pinned photodiode
Maximum framerate (burst) [fps]	2.18M	20M	100M	25M	N/A
Maximum framerate (continuous) [fps]	3k	7.8k	N/A	N/A	80k
Readout noise [e- RMS]	0	5	N/A	N/A	23
Photon detection efficiency/ Quantum efficiency (peak) [%]	55	N/A	N/A	N/A	N/A
Resolution	128×128	400×250	50×108	32×32	1280×832
Data rate (burst) [Mpix/s]	3.6E+10	2.0E+12	5.4E+11	2.6E+10	N/A
Data rate (continuous) [Mpix/s]	1.6E+07	7.8E+08	N/A	N/A	8.5E+10
Architecture	In-pixel memory	Column memory	In-pixel memory	In-pixel memory	Parallel readout
Memory type	Shift register	N/A	Trench capacitor	CCD gate	N/A
Burst length [frames]	32	256	368	1220	N/A
Pixel size [μm^2]	40.68×40.68	32×32	70×35	72.56×72.56	18.54×18.54
Fill factor [%]	~100	63	24	~100	N/A
Full well [e-]	31	10k	N/A	3k	9k
Power consumption [W]	1	10	N/A	N/A	<40

Conclusions

- A successful operation of a SPAD array at 2.18M fps has been shown, demonstrating its feasibility for a single-photon counting ultra high-speed image sensor.
- The pixel has a 5-bit depth, limiting the maximum photon count to 31, constraining the dynamic range.
- Future improvements are expected to enhance both high-speed frames and photon counts to be more adaptable to different application requirements.

References

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5. S. Manabu, R. Kuroda, and S. Sugawa, “Over 100 Million Frames per Second 368 Frames Global Shutter Burst CMOS Image Sensor with In-pixel Trench Capacitor Memory Array,” in *Proceedings of the 2019 International Image Sensor Workshop*, pp. 23-27, Snowbird, UT, USA, 2019.
6. V. Dao, N. Ngo, A. Q. Nguyen, K. Morimoto, K. Shimonomura, P. Goetschalckx, L. Haspeslagh, P. De Moor, K. Takehara, and T. G. Etoh, “An image signal accumulation multi-collection-gate image sensor operating at 25 Mfps with 32× 32 pixels and 1220 in-pixel frame memory,” in Sensors, vol. 18, no. 9 (2018): 3112.

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- **Ahmet T Erdogan** for firmware development and understanding.
- **Lars Fisher** for PCB design.
- **Robert K Henderson** for supervision and guidance.
- **STMicroelectronics** for chip fabrication

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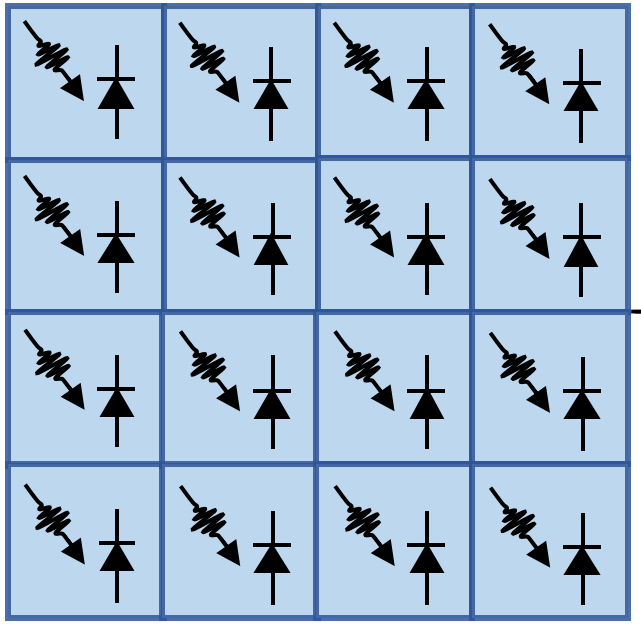
Backup Slides

Macropixel Architecture

Top tier:
passively-quenched SPADs



Bottom tier: pixel logic circuits